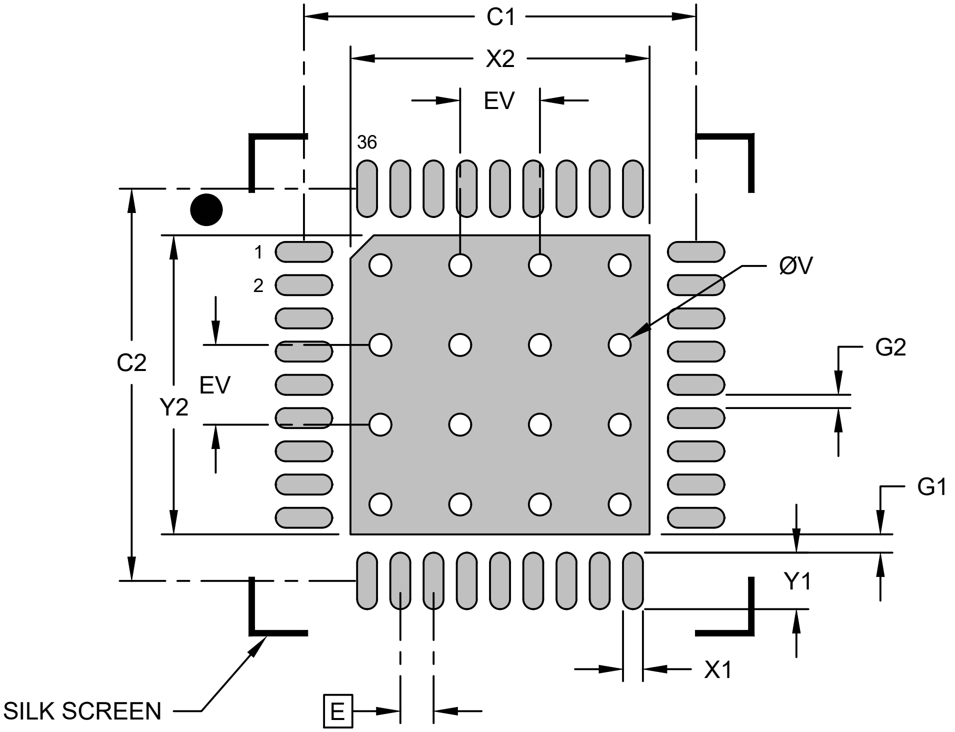
36-Lead Very Thin Plastic Quad Flat, No Lead Package (LNX) - 6x6x1.0 mm Body [VQFN] With 4.4 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Center Pad Width	X2			4.50
Center Pad Length	Y2			4.50
Contact Pad Spacing	C1		5.90	
Contact Pad Spacing	C2		5.90	
Contact Pad Width (Xnn)	X1			0.30
Contact Pad Length (Xnn)	Y1			0.85
Contact Pad to Center Pad (Xnn)	G1	0.20		
Contact Pad to Contact Pad (Xnn)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.